

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
ISOW7740DFMR	Active	Production	SOIC (DFM) 20	850 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7740
ISOW7740DFMR.A	Active	Production	SOIC (DFM) 20	850 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7740
ISOW7740DFMR.B	Active	Production	SOIC (DFM) 20	850 LARGE T&R	-	Call TI	Call TI	-40 to 125	
ISOW7740FDFMR	Active	Production	SOIC (DFM) 20	850 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7740F
ISOW7740FDFMR.A	Active	Production	SOIC (DFM) 20	850 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7740F
ISOW7740FDFMR.B	Active	Production	SOIC (DFM) 20	850 LARGE T&R	-	Call TI	Call TI	-40 to 125	
ISOW7741BDFMR	Active	Production	SOIC (DFM) 20	850 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7741
ISOW7741BDFMR.A	Active	Production	SOIC (DFM) 20	850 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7741
ISOW7741BDFMR.B	Active	Production	SOIC (DFM) 20	850 LARGE T&R	-	Call TI	Call TI	-40 to 125	
ISOW7741DFMR	Active	Production	SOIC (DFM) 20	850 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7741
ISOW7741DFMR.A	Active	Production	SOIC (DFM) 20	850 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7741
ISOW7741DFMR.B	Active	Production	SOIC (DFM) 20	850 LARGE T&R	-	Call TI	Call TI	-40 to 125	
ISOW7741FBDFMR	Active	Production	SOIC (DFM) 20	850 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7741F
ISOW7741FBDFMR.A	Active	Production	SOIC (DFM) 20	850 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7741F
ISOW7741FBDFMR.B	Active	Production	SOIC (DFM) 20	850 LARGE T&R	-	Call TI	Call TI	-40 to 125	
ISOW7741FDFMR	Active	Production	SOIC (DFM) 20	850 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7741F
ISOW7741FDFMR.A	Active	Production	SOIC (DFM) 20	850 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7741F
ISOW7741FDFMR.B	Active	Production	SOIC (DFM) 20	850 LARGE T&R	-	Call TI	Call TI	-40 to 125	
ISOW7742DFMR	Active	Production	SOIC (DFM) 20	850 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7742
ISOW7742DFMR.A	Active	Production	SOIC (DFM) 20	850 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7742
ISOW7742DFMR.B	Active	Production	SOIC (DFM) 20	850 LARGE T&R	-	Call TI	Call TI	-40 to 125	
ISOW7742FDFMR	Active	Production	SOIC (DFM) 20	850 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7742F
ISOW7742FDFMR.A	Active	Production	SOIC (DFM) 20	850 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7742F
ISOW7742FDFMR.B	Active	Production	SOIC (DFM) 20	850 LARGE T&R	-	Call TI	Call TI	-40 to 125	
ISOW7743DFMR	Active	Production	SOIC (DFM) 20	850 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7743
ISOW7743DFMR.A	Active	Production	SOIC (DFM) 20	850 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7743
ISOW7743DFMR.B	Active	Production	SOIC (DFM) 20	850 LARGE T&R	-	Call TI	Call TI	-40 to 125	
ISOW7743FDFMR	Active	Production	SOIC (DFM) 20	850 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7743F
ISOW7743FDFMR.A	Active	Production	SOIC (DFM) 20	850 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7743F

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ISOW7743FDFMR.B	Active	Production	SOIC (DFM) 20	850 LARGE T&R	-	Call TI	Call TI	-40 to 125	
ISOW7744DFMR	Active	Production	SOIC (DFM) 20	850 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7744
ISOW7744DFMR.A	Active	Production	SOIC (DFM) 20	850 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7744
ISOW7744DFMR.B	Active	Production	SOIC (DFM) 20	850 LARGE T&R	-	Call TI	Call TI	-40 to 125	
ISOW7744FDFMR	Active	Production	SOIC (DFM) 20	850 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7744F
ISOW7744FDFMR.A	Active	Production	SOIC (DFM) 20	850 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	ISOW7744F
ISOW7744FDFMR.B	Active	Production	SOIC (DFM) 20	850 LARGE T&R	-	Call TI	Call TI	-40 to 125	

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF ISOW7741, ISOW7742 :

- Automotive : [ISOW7741-Q1](#), [ISOW7742-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects